

#### AP15P06S Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP15P06S	SOP-8L	AP15P06S XXX YYYY	3000

#### AP15P06S Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-60	V
VGS	Gate-Source Voltage	±20	V
I₀@Tc=25°C	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-15	A
I₀@Tc=100℃	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-8.5	A
IDM	Pulsed Drain Current <sup>2</sup>	-45	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	113	mJ
P₀@Tc=25℃	Total Power Dissipation <sup>4</sup>	52.1	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R₀JA	Thermal Resistance Junction-Ambient <sup>1</sup>	85	°C/W
R₀JC	Thermal Resistance Junction-Case <sup>1</sup>	Thermal Resistance Junction-Case <sup>1</sup> 2.4	



### AP15P06S Electrical Characteristics (Tc=25 $^{\circ}$ Cunless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-60	-68		V
$\triangle BVDSS/ \triangle TJ$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25 $^\circ\!\!\!{\rm C}$ , I_D=-1mA		-0.035		V/℃
	Statia Drain Source On Registeres <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-12A	20 28			
RDS(ON)	S(ON) Static Drain-Source On-Resistance <sup>2</sup> V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-8A			26	33	mΩ
VGS(th)	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.0	-1.6	-2.5	V
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS-VDS , ID2300A		4.28		mV/°C
IDSS	Drain-Source Leakage Current	$V_{\text{DS}}\text{=-}48\text{V}$ , $V_{\text{GS}}\text{=}0\text{V}$ , T_J=25 $^\circ\!\!\mathbb{C}$			1	– uA
1033	Drain-Source Leakage Current	$V_{\text{DS}}\text{=-}48V$ , $V_{\text{GS}}\text{=}0V$ , $T_{\text{J}}\text{=}55^\circ\!\!\mathbb{C}$			5	
IGSS	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	_		±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =-10V , I <sub>D</sub> =-18A		23		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		7		Ω
Qg	Total Gate Charge (-4.5V)			25	-	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =-20V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =- 12A		6.7		
$Q_gd$	Gate-Drain Charge			5.5		
Td(on)	Turn-On Delay Time			38		
Tr	Rise Time	V <sub>DD</sub> =-15V , V <sub>GS</sub> =-10V , R <sub>G</sub> =3.3Ω,		23.6		
Td(off)	Turn-Off Delay Time	I <sub>D</sub> =-1A		100		ns
T <sub>f</sub>	Fall Time			6.8		
Ciss	Input Capacitance			3635		
Coss	Output Capacitance	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz		224		pF
Crss	Reverse Transfer Capacitance			141		
ls	Continuous Source Current <sup>1,5</sup>				-35	Α
ISM	Pulsed Source Current <sup>2,5</sup>	<ul> <li>V<sub>G</sub>=V<sub>D</sub>=0V , Force Current</li> </ul>			-70	А
VSD	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25℃			-1	V

Note :

1. The data tested by surface mounted on a 1 inch 2  $\,$  FR-4 board with 2OZ copper.

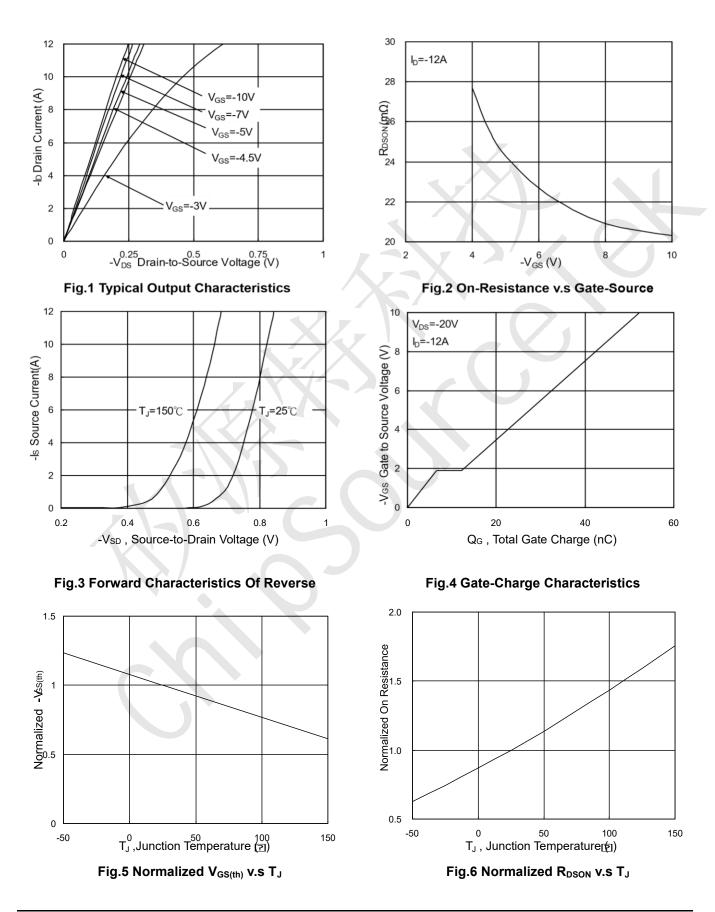
2、 The data tested by pulsed , pulse width  $\leq 300 \text{us}$  , duty cycle  $\leq 2\%$ 

- 3、The EAS data shows Max. rating . The test condition is VDD=-48V,VGS =-10V,L=0.1mH,IAS =-47.6A
- 4、The power dissipation is limited by 150°C junction temperature

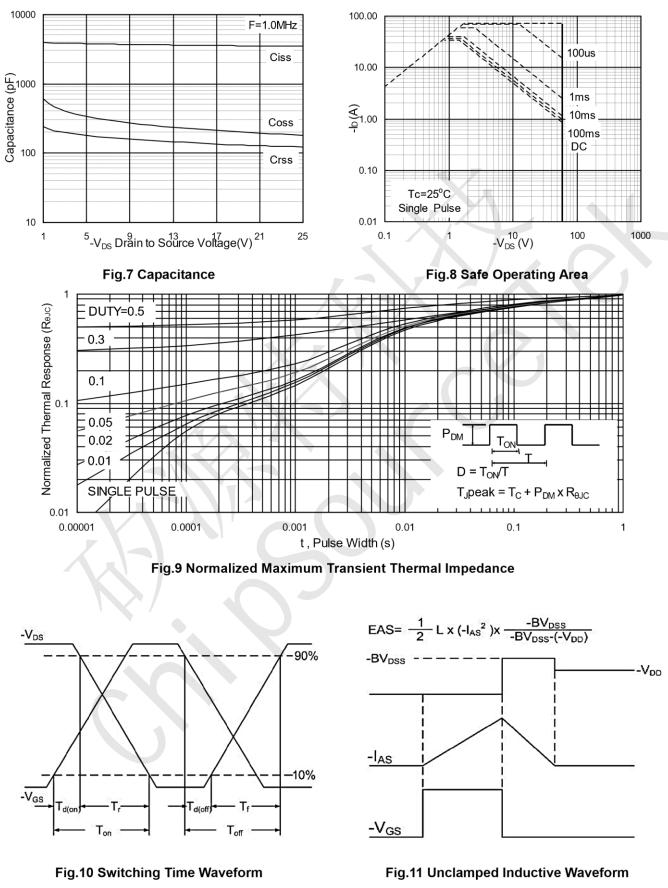
5、The data is theoretically the same as I D and I DM, in real applications, should be limited by total power dissipation.



### AP15P06S Typical Characteristics

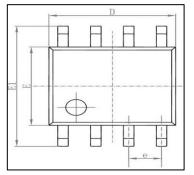


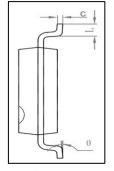


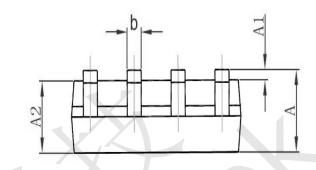




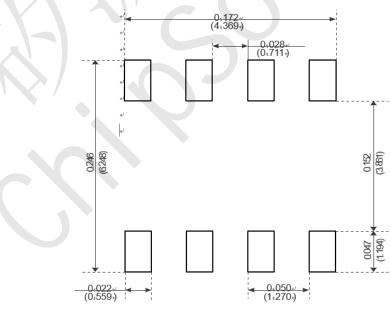
### AP15P06S Package Mechanical Data-SOP-8L







Comback	Dimensions Ir	n Millimeters	Dimensions	In Inches
Symbol	Min	Max	Min	Max
A	1.350	1.750	0. 053	0.069
A1	0.100	0. 250	0.004	0.010
A2	1. 350	1. 550	0. 053	0.061
b	0. 330	0. 510	0.013	0. 020
с	0. 170	0. 250	0.006	0.010
D	4. 700	5. 100	0. 185	0. 200
E	3.800	4.000	0.150	0. 157
E1	5.800	6. 200	0. 228	0. 244
е	1.270	(BSC)	0. 050	(BSC)
L	0. 400	1. 270	0.016	0.050
θ	<b>0</b> °	8°	0°	8°



Recommended Minimum Pads-



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Edition	Date	Change
Rve1.0	2022/1/31	Initial release

